



# Product data sheet

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# SS1045 THRU SS10100 HF

Semiconductor Compiance



SMC

#### EATURES

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

#### MECHANICAL DATA

- Case: SMC
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.22g /0.0077oz

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS1045	SS1060	SS10100	Units
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	45	60	100	V
Maximum RMS voltage	V <sub>RMS</sub>	32	42	70	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	45	60	100	V
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>		10.0		А
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	150			A
Max Instantaneous Forward Voltage @10.0 A	V <sub>F</sub>	0.55	0.75	0.90	V
Maximum DC Reverse Current $T_j = 25^{\circ}C$ at Rated DC Reverse Voltage $T_j = 100^{\circ}C$	I <sub>R</sub>	0.5 50		mA	
Typical Thermal Resistance	R <sub>0JA</sub>	20			°C/W
Operating Junction Temperature Range	Tj	-55 ~ +150			°C
Storage Temperature Range	T <sub>stg</sub>	-55 ~ +150			°C

(1) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



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Fig.1 Forward Current Derating Curve

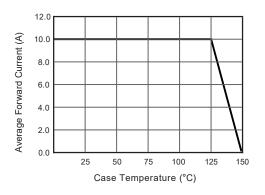
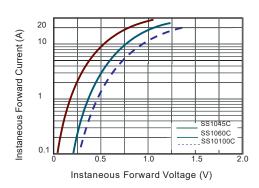
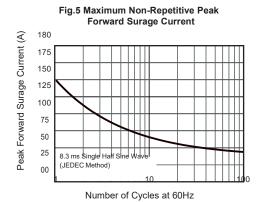


Fig.3 Typical Forward Characteristic





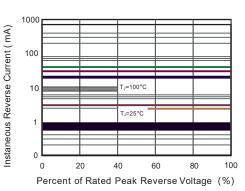


Fig.4- Typical Transient Thermal Impedance

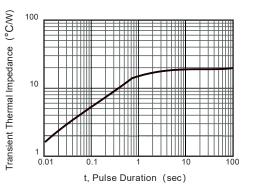


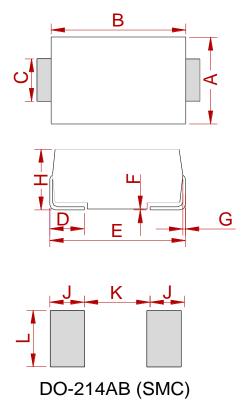
Fig.2 Typical Reverse Characteristics



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### PACKAGE MECHANICAL DATA



	Dimensions					
Ref.	Millin	Millimeters		Inches		
	Min.	Max.	Min.	Max.		
A	5.75	6.25	0.226	0.246		
В	6.90	7.40	0.272	0.291		
С	2.75	3.25	0.108	0.128		
D	0.95	1.52	0.037	0.060		
E	7.70	8.20	0.303	0.323		
F	0.051	0.203	0.002	0.008		
G	0.15	0.31	0.006	0.012		
Н	2.15	2.62	0.085	0.103		
J	2.40		0.094			
К		4.20		0.165		
L	3.30		0.130			

## **REEL SPECIFICATION**

P/N	PKG	QTY
SS1045 THRU SS10100	SMC	3000



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